

In the Claims:

1. (Currently Amended) An electronic unit comprising:
 - a module in which a semiconductor device is attached on a bottom of a circuit board and which has lands provided on the bottom of the circuit board with the lands being connected to the semiconductor device; and
 - a printed circuit board on which the module is mounted,
 - the printed circuit board having electrical conductors and having a hole in a position facing the semiconductor device ~~and having electrical conductors to which the lands are soldered,~~
 - wherein solder balls are applied on the lands, a wall of the hole has recesses having electrical conductors applied to the recesses to receive the corresponding solder balls, and the module is mounted on the printed circuit board by soldering the lands to the electrical conductors while the semiconductor device is disposed in the hole.
2. – 3. (Cancelled)
4. (New) The electronic module of claim 1, wherein the printed circuit board includes a wiring pattern disposed between laminated layers, the wiring pattern connected to the electrical conductors.